



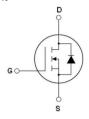
N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced super junction technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- ◆ Optimized body diode reverse recovery performance
- ◆ Low on-resistance and low conduction losses
- ◆ Small package
- ◆ Ultra Low Gate Charge cause lower driving requirements
- ◆ 100% Avalanche Tested
- ROHS compliant





Schematic diagram

TO-220F

Application

- ◆ Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- ◆ Uninterruptible Power Supply (UPS)
- ◆ LLC Half-bridge

Vos	650	٧
R _{DS(ON)} typ	160	mΩ
l _D	21	А

Package Marking And Ordering Information

Device	Device Package	Marking
MJ65TF180F	TO-220F	MJ65TF180F

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	MJ65TF180F	Unit
Drain-Source Voltage (Vcs=0V)	VDS	650	V
Gate-Source Voltage (Vps=0V) AC (f>1 Hz)	Vgs	±30	V
Continuous Drain Current at Tc=25°C	ID (DC)	21*	А
Continuous Drain Current at Tc=100°C	ID (DC)	13.2*	А
Pulsed drain current (Note 1)	IDM (pluse)	84*	А
Maximum Power Dissipation (Tc=25℃)	Po	33.8	W
Derate above 25°C	PD	0.27	W/°C
Single pulse avalanche energy (Note 2)	Eas	441	mJ
Avalanche current (Note 1)	lar	10.5	А
Repetitive Avalanche energy, tar limited by T _{jmax} (Note 1)	Ear	0.7	mJ

Parameter	Symbol	MJ65TF180F	Unit
Drain Source voltage slope, V _{DS} ≤480 V	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	TJ,TsTG	-55+150	°C





Table 2. Thermal Characteristic

Parameter	Symbol	MJ65TF180F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	RthJC	3.69	°C/W
Thermal Resistance, Junction-to-Ambient (Maximum)	RthJA	80	°C/W

Table 3. Electrical Characteristics (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Uni
On/off states						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250μA	650	-	-	V
Zero Gate Voltage Drain Current (Tc=25°C)	loss	V _{DS} =650V,V _{GS} =0V	-	-	2	μΑ
Zero Gate Voltage Drain Current (Tc=125°C)	loss	V _{DS} =650V,V _{GS} =0V	-	-	100	μΑ
Gate-Body Leakage Current	lgss	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	3	3.5	4	V
Drain-Source On-State Resistance	Rds(on)	V _{GS} =10V,I _D =10.5A	-	160	199	mΩ
Dynamic Characteristics				1		
Input Capacitance	Cies	V _{DS} =50V,V _{GS} =0V	-	2250	-	PF
Output Capacitance	Coss	F=1.0MHz	-	83	-	PF
Effective output capacitance, energy related	C _{o(er)}	V _{GS} =0 V,V _{DS} =0480 V	-	48	-	pF
Effective output capacitance, time related	C _O (tr)	I _D =constant, V _G s=0 V V _D s=0480V	-	200	-	pF
Total Gate Charge	Qg		-	36	-	nC
Gate-Source Charge	Qgs	V _{DS} =480V,I _D =21A V _{GS} =10V	-	14	-	nC
Gate-Drain Charge	Qgd		-	8.5	-	nC
Switching times						
Turn-on Delay Time	t _{d(on)}		-	11	-	nS
Turn-on Rise Time	tr	Vpp=380V.lp=11A	-	6	-	nS
Turn-Off Delay Time	t _{d(off)}	$R_G=4\Omega,V_{GS}=10V$	-	61	-	nS
Turn-Off Fall Time	tr		-	4.5	-	nS
Source- Drain Diode Characteristics	I				ı	
Source-drain current (Body Diode)	Isp		-	-	21	А
Pulsed Source-drain current (Body Diode)	Isdm	Tc=25°C	-	-	84	А
Forward On Voltage	Vsp	Tj=25°C,IsD=21A,Vgs=0V	-	0.9	1.3	V
Reverse Recovery Time	trr		-	160	_	nS
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =11A di/dt=100A/µs	-	1.4	_	uC
Peak reverse recovery Current	Irrm		_	17	_	Α

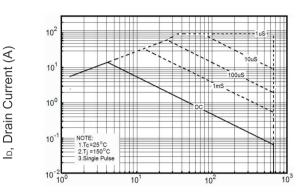




Notes

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature
- $2.T_j = 25^{\circ}C, V_{DD} = 50V, V_{G} = 10V, R_{G} = 25\Omega$

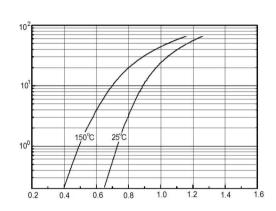
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)



lor, Reverse Drain Current(A)

lb, Drain Current (A)

RDS(ON), Drain-Source



V_{DS}, Drain-Source Voltage (V)

Figure 1 Safe operating area

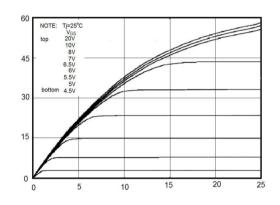
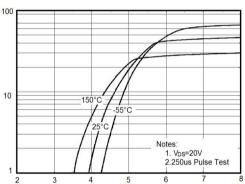
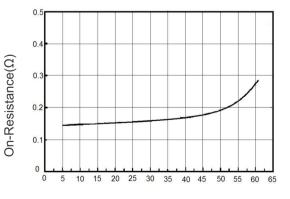


Figure 2 Source-Drain Diode Forward Voltage



Vsp,Source-Drain Voltage(V)

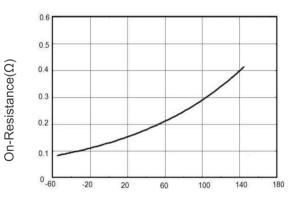
V_{DS}(V) Figure 3 Output characteristics



RDS(ON), Drain-Source

V_{GS}, Gate-Source Voltage (V)

Figure 4 Transfer characteristics



ID, Drain Current (A)

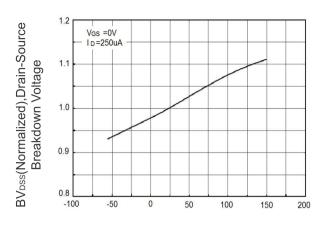
Figure 5 Static drain-source on resistance

T_J, Junction Temperature (°C) Figure 6 RDS(ON) vs Junction Temperature

lo, Drain Current (A)

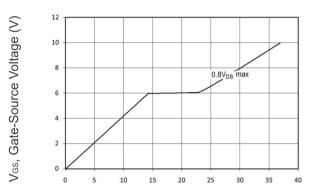
Capacitances(pF)





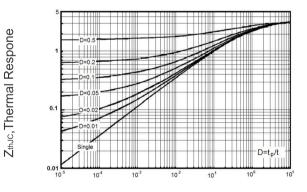
T_J, Junction Temperature (°C)

Figure 7 BVDSS vs Junction Temperature



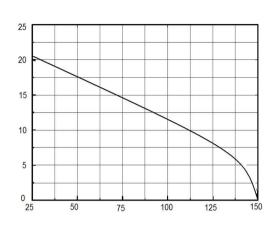
Q_G,Total Gate Charge(nC)

Figure 9 Gate charge waveforms



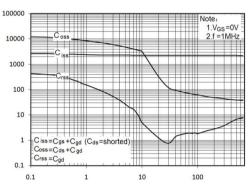
t₅,Square Wave Pulse(S)

Figure 11 Transient Thermal Impedance



Tc, Case Temperature (°C)

Figure 8 Maximum I_D vs Junction Temperature



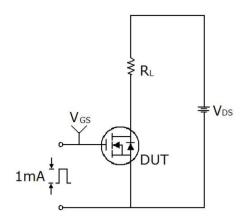
V_{DS}, Drain-Source Voltage (V)

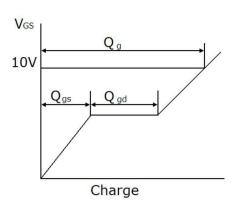
Figure 10 Capacitance



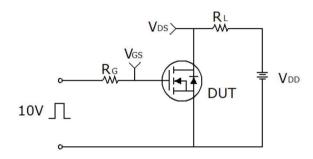


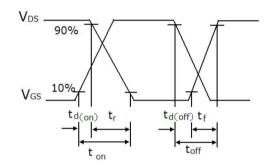
Test circuit



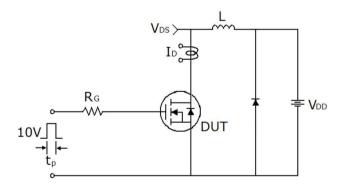


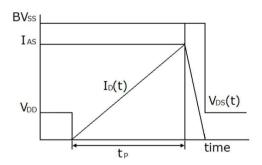
Gate charge test circuit & Waveform





Switch Time Test Circuit



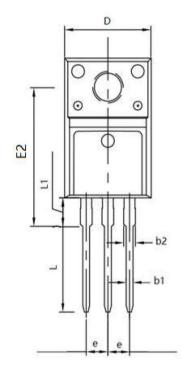


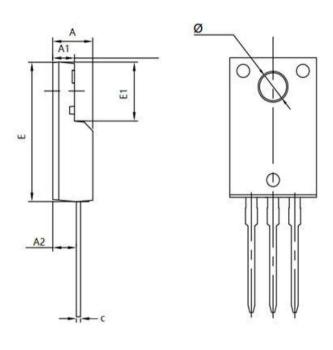
Unclamped Inductive Switching Test Circuit & Waveforms





TO-220F Package Information





Symbol	Dimensions	In Millimeters	Dimension	s In Inches	
	Min.	Max.	Min.	Max.	
А	4.500	4.900	0.177	0.193	
A1	2.340	2.740	0.092	0.108	
A2	2.560	2.960	0.101	0.117	
b1	0.700	0.900	0.028	0.035	
b2	1.180	1.580	0.046	0.062	
С	0.400	0.600	0.016	0.024	
D	9.960	10.360	0.392	0.408	
E	15.670	15.970	0.617	0.629	
E1	6.500	6.900	0.256	0.272	
E2	15.500	16.100	0.610	0.634	
е	2.540) TYP	0.100	TYP	
Ф	3.080	3.280	0.121	0.129	
L	12.640	13.240	0.498	0.521	
L1	3.030	3.430	0.119	0.135	





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